

58th ECTC Best and Outstanding Papers

The Electronic Components and Technology Conference is pleased to announce the “Best and Outstanding Papers” selected from the 58th ECTC technical sessions held in Orlando, Florida in 2008.

The authors of the Best Session Paper share a check for \$2500 and the authors of the Best Poster Paper share a check for \$1500. The authors of the Outstanding Session Paper share a check for \$1000 and the authors of Outstanding Poster Paper share a check for \$1000.

Commemorating their achievement, the winning authors will also be presented with personalized plaques at 59th ECTC during the luncheon on Wednesday, May 27, 2009.

Best Session Paper

(Session 29, Paper 1)

Material Design and Package-Level Reliability of a Novel Low-Temperature Solder Based on Intermetallic-Compound Phases with Superior High-Homologous Temperature Properties

Daewoong Suh and Chi-Won Hwang – Intel Corporation; Minoru Ueshima and Jun Sugimoto – Senju Metal Industry Company, Limited

Best Poster Paper

(Session 28, Paper 11)

Development of a 50mm Dual Flip Chip Plastic Land Grid Array Package for Server Applications

Sylvain Ouimet and Isabelle Dépatie – IBM Canada Limited; Jon Casey, Kenneth Marston, Jennifer Muncy, Virendra Jadhav, and Thomas Wassick – IBM Semiconductor Research and Development Center; John Corbin – IBM Systems and Technology Group

Outstanding Session Paper

(Session 14, Paper 7)

Replacement of the Drop Test with The Vibration Test-The Effect of Test Temperature on Reliability

T.T. Mattila, L. Suotula, and J.K. Kivilahti – Helsinki University of Technology

Outstanding Poster Paper

(Session 37, Paper 21)

Interfacial Fracture Properties and Failure Modeling for Microelectronics

A. Xiao, K.M.B. Jansen, J. de Vreugd, and L.J. Ernst – Delft University of Technology; H. Pape – Infineon Technologies AG; B. Wunderle – Fraunhofer IZM